



PRESS RELEASE

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High-Performance IC Substrate Manufacturing at an Inflection Point

Driven by advanced packaging substrate needs, the industry has reached an inflection point in IC substrate manufacturing. Increasing I/O counts are driving substrate layer counts to more than 20. Larger die sizes and multiple die mounted on the substrate are driving the need for larger body sizes, up to 100 mm x 100 mm. Some companies use a silicon interposer with multiple redistribution layers (RDLs) to provide the connection between logic and high bandwidth memory (HBM). Others use fan-out on substrate with RDLs. A number of companies are considering new RDL on organic solutions with 2µm line width and spaces and Intel is exploring an expanded role for its Embedded Multi-die Interconnect Bridge (EMIB). Several companies are making investments in fab-like processing equipment for the next generation IC packaging substrates. These developments are described and a forecast for high-density substrates is provided in TechSearch International's newest Advanced Packaging Update.

TechSearch International's annual survey on substrate design rules is highlighted, with special coverage of suppliers of laminate flip chip BGA and CSP substrates worldwide. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

The latest Advanced Packaging Update is an 83-page report with full references and an accompanying set of 41 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 18,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see www.techsearchinc.com. Follow us on twitter @Jan_TechSearch